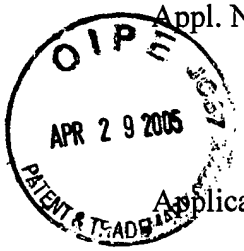
PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos Karnezos)
) Examiner: Alonzo Chambliss
Application No.: 10/681,735)
) Group Art Unit: 2814
Filed: October 8, 2003)
) Date: April 26, 2005 .
Title: **Semiconductor multi-package module having inverted land grid array (LGA) package stacked over ball grid array (BGA) package**)
) CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: MS Amendment, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on 26 April 2005 .

Signed _____
Bill Kennedy

AMENDMENT

Dear Sir:

Responsive to the Office action mailed October 26, 2004, kindly amend the application as follows.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the **Listing of Claims**, which begins on page 5 of this paper.

Amendments to the Drawings begin on page 9 of this paper and include both an attached replacement sheet and an annotated sheet showing changes.

Remarks begin on page 10 of this paper.

An **Appendix** including amended drawing figures is attached following page 17 of this paper.